

SOT684-14

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

21 April 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	13-7-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	0.8	-	0.85	1	mm
A ₂	package height	-	-	-	-	
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	56	-	



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2. Package outline

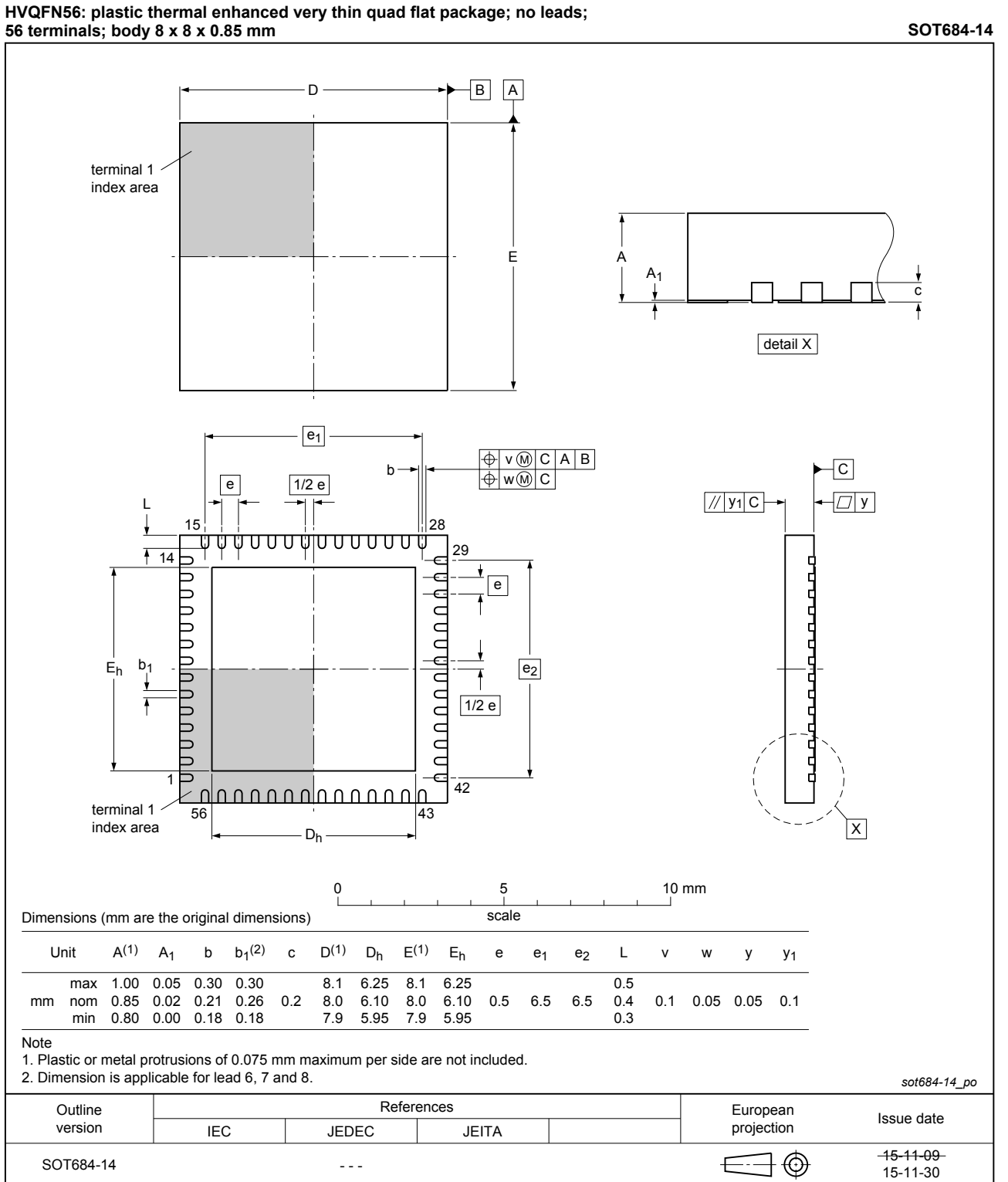


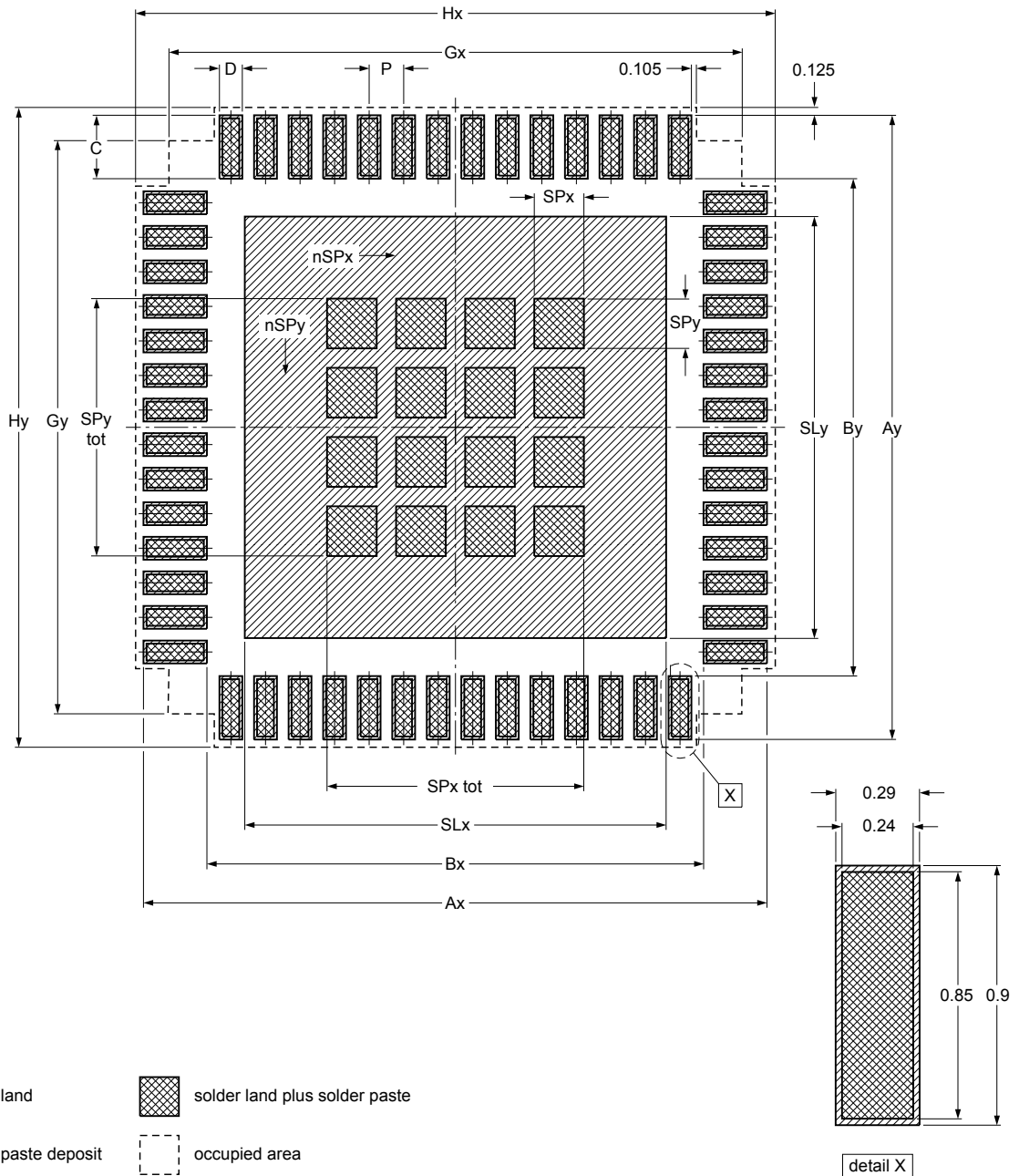
Fig. 1. Package outline HVQFN56 (SOT684-14)

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3. Soldering

Footprint information for reflow soldering of HVQFN56 package

SOT684-14



Dimensions in mm		Recommended stencil thickness: 0.1 mm																	
P	Ax	Ay	Bx	By	SLx	SLy	SPx	SPy	SPx tot	SPy tot	C	D	nSPx	nSPy	Gx	Gy	Hx	Hy	
0.5	9.0	9.0	7.2	7.2	6.1	6.1	0.7	0.7	3.7	3.7	0.9	0.29	4	4	8.3	8.3	9.25	9.25	
Issue date	15-12-02 15-12-10																		

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Fig. 2. Reflow soldering footprint for HVQFN56 (SOT684-14)

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4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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